Enable High Flux and Cost Efficient System

Z Power Chip on board – ZC series, ZC12

SDW02F1C, SDW82F1C

LM-80 | RoHS | MacAdam 3-Step

Product Brief

Description

- The ZC series are LED arrays which provide High Flux and High Efficacy.
- It is especially designed for easy assembly of Lighting fixtures by eliminating reflow soldering process.
- It's thermal management is excellent than other power LED solutions with wider Metal area.
- ZC series are ideal light sources for General Lighting applications including Replacement Lamps, Industrial & Commercial Lightings and other high Lumen required applications.

Features and Benefits

- High Efficacy typ. 135lm/W
- Flux range from 1,440 ~ 2,310lm
- Power dissipation 13 ~ 18.5W
- Wide CCT range with CRI 70~80
- MacAdam 3-step binning
- Uniformed Shadow
- Excellent Thermal management

Key Applications

- Bulb - Replacement Lamps
- Down Lighting – Commercial Lighting
- High Bay - Industrial Lighting
- Architectural Lighting
- Decorative / Pathway Lighting

Table 1. Product Selection Table

Part Number	CCT			
	Color	Min.	Typ.	Max.
SDW02F1C	Cool White	4700K	5300K	6000K
SDW82F1C	Neutral White	3700K	4000K	4200K
SDW82F1C	Warm White		3000K	
SDW82F1C	Warm White		2700K	

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Performance Characteristics

Table 2. Product Selection Guide, T_c = 25ºC, RH30%

Part Number	CCT (K) [1]	Typical Luminous Flux [2] Φ_V [3] (lm)		Typical Forward Voltage (V_F) [4]		CRI [5], R_a	Viewing Angle (degrees) 2Θ ½
	Typ.	350mA	480mA*	350mA	480mA*	Min.	Typ.
SDW02F1C	5000	1780	2310	37	38.5	70	120
SDW82F1C	4000	1620	2100	37	38.5	80	120
SDW82F1C	3000	1500	1950	37	38.5	80	120
SDW82F1C	2700	1440	1870	37	38.5	80	120

Notes :

(1) Correlated Color Temperature is derived from the CIE 1931 Chromaticity diagram. Color coordinate : ±0.01, CCT ±5% tolerance.

(2) Seoul Semiconductor maintains a tolerance of ±7% on flux and power measurements.

(3) Φ_V is the total luminous flux output as measured with an integrating sphere.

(4) Tolerance is ±2.5V on forward voltage measurements.

(5) Tolerance is ±2 on CRI measurements.

Performance Characteristics

Table 3. Characteristics, T_c = 25ºC, RH30%

Parameter	Symbol	Value			Unit
		Min.	Typ.	Max.	
Forward Current	I_F	-	0.35	0.48	A
Power Dissipation	P_d	-	13.0	18.5	W
Junction Temperature	T_j	-	-	125	ºC
Operating Temperature	T_{opr}	-40	-	85	ºC
Storage Temperature	T_{stg}	-40	-	100	ºC
Thermal resistance (J to S) [1]	$R\theta_{J-S}$	-	0.7	-	K/W
ESD Sensitivity(HBM) [2]	-	-	-	±8	kV

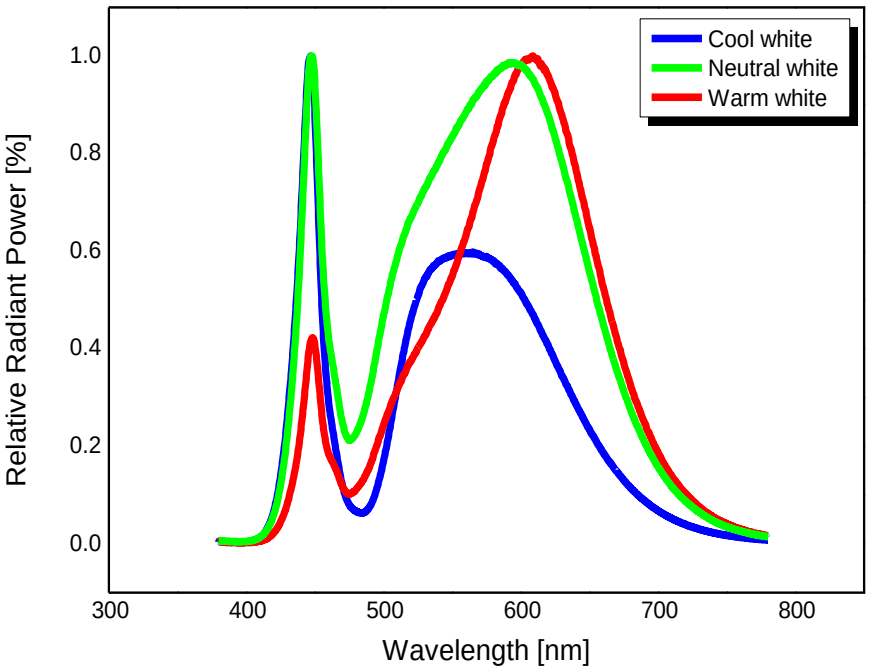
Notes :

(1) Thermal Resistance : $R\theta_{J-S}$ (Junction to COB's metal PCB)

(2) A zener diode is included to protect the product from ESD.

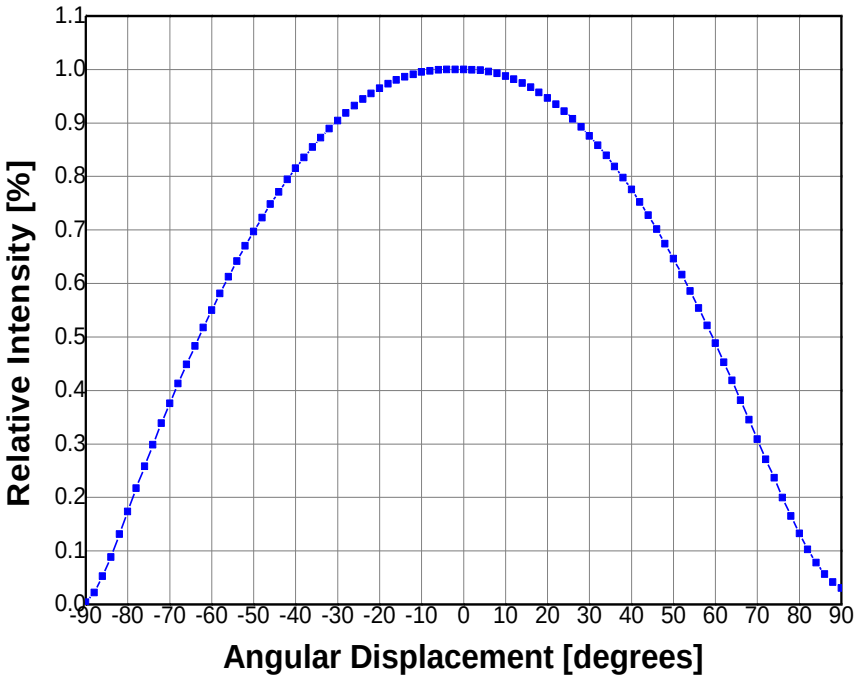
Relative Spectral Distribution

Fig 1. Color Spectrum, T_c = 25℃, I_F = 350mA, RH30%



Luminous Flux Characteristics

Fig 2. Radiant pattern, I_F = 350mA



Forward Current Characteristics

Fig 3. Forward Voltage vs. Forward Current , T_c =25℃

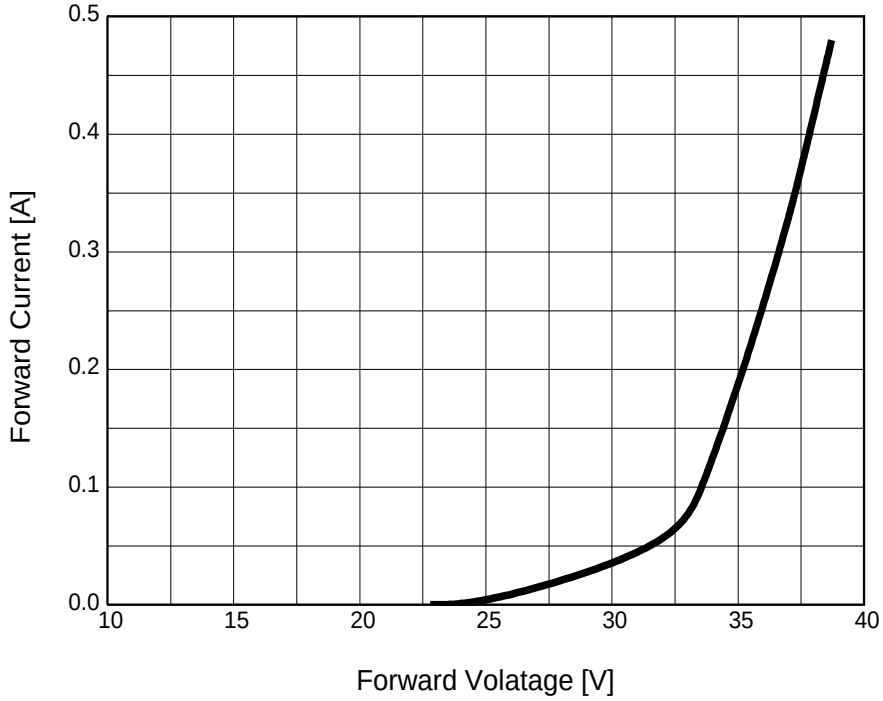
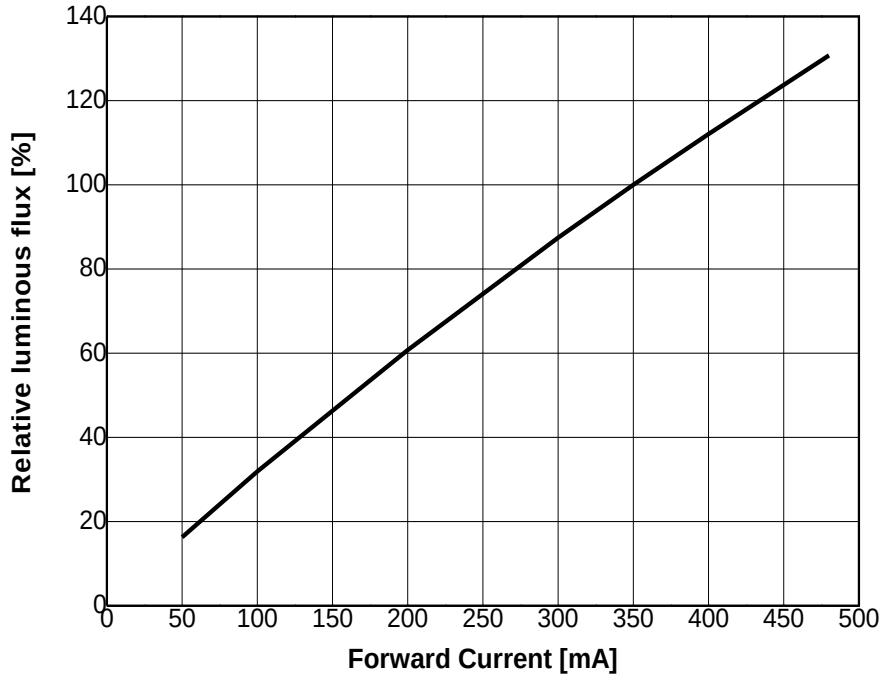
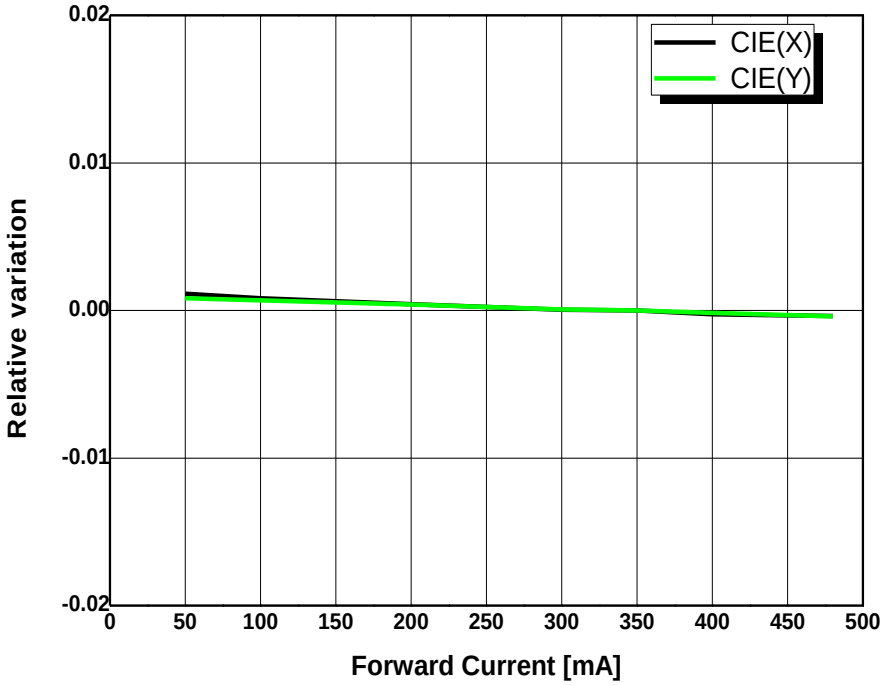


Fig 4. Forward Current vs. Relative Luminous Flux, T_c =25℃



Forward Current Characteristics

Fig 5. Forward Current vs. CIE X, Y Shift , T_c =25℃ (Warm white)



Junction Temperature Characteristics

Fig 6. Relative Light Output vs. Junction Temperature, I_F = 350mA

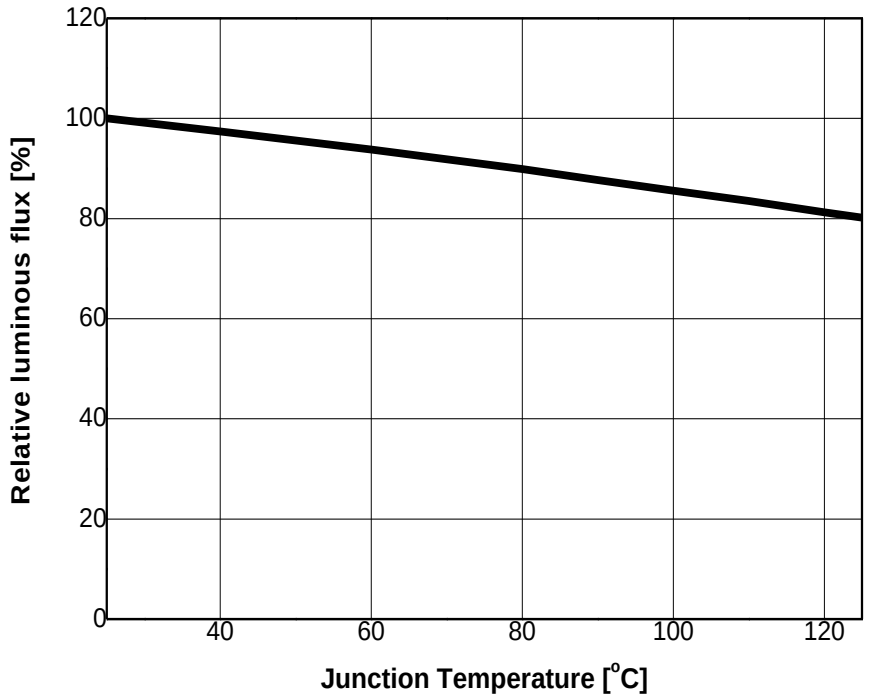
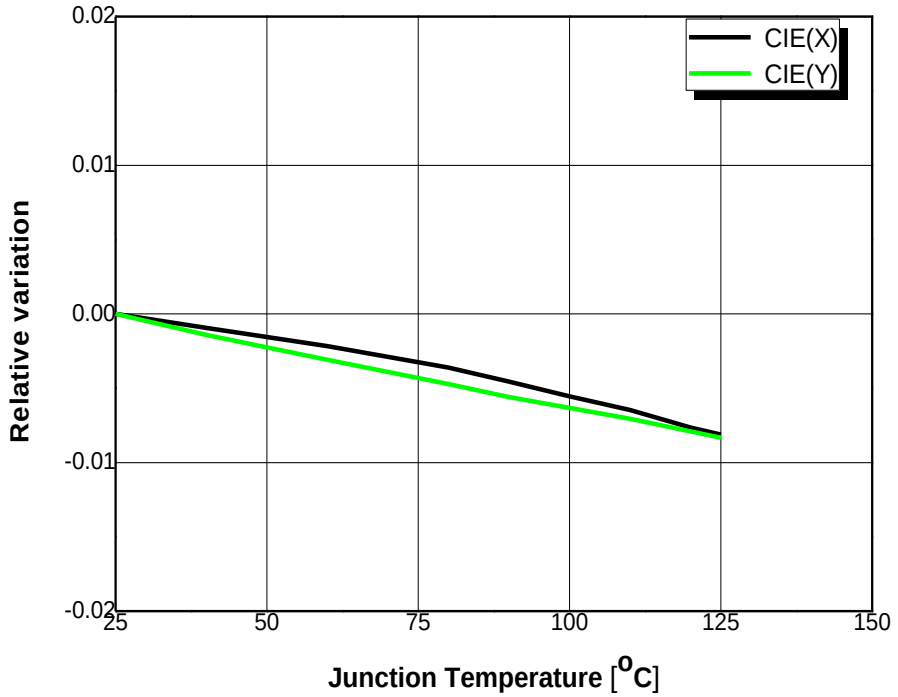
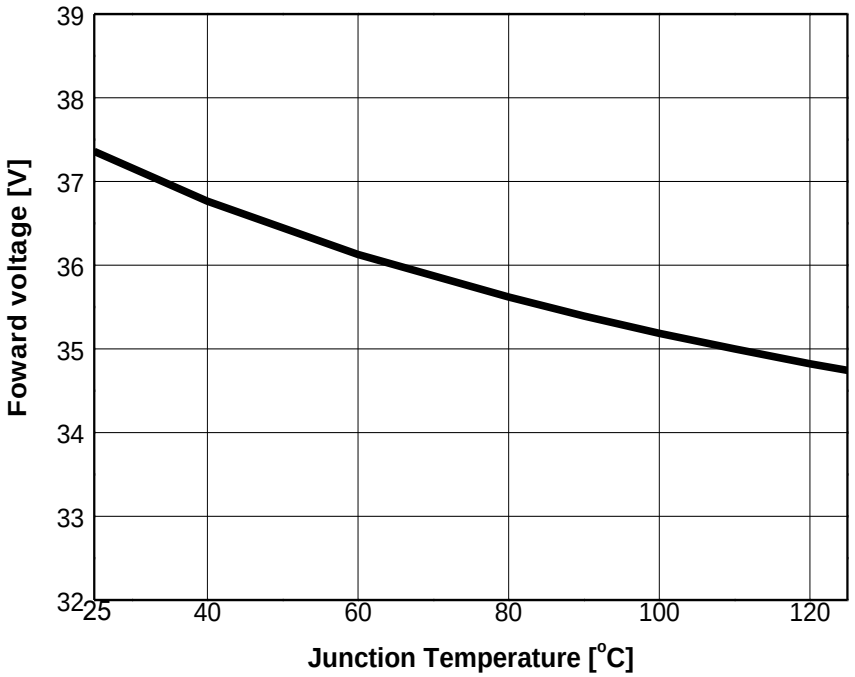


Fig 7. Junction Temp. vs. CIE X, Y Shift, I_F = 350mA (Warm white)



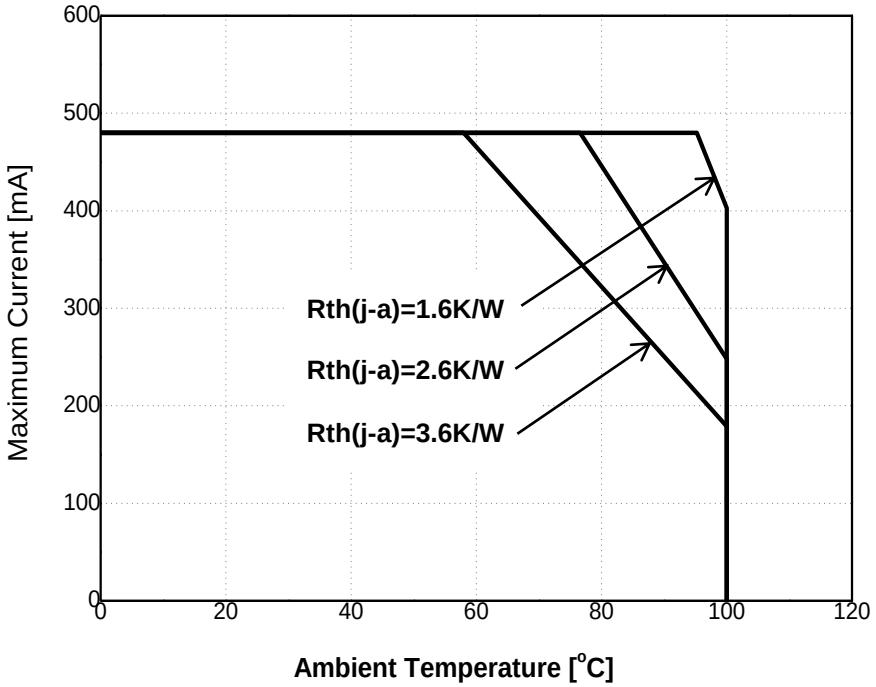
Junction Temperature Characteristics

Fig 8. Forward Voltage vs. Junction Temperature, I_F = 350mA



Ambient Temperature Characteristics

Fig 9. Maximum Forward Current vs. Ambient Temperature, T_j(max.) = 125℃, I_F = 0.48A



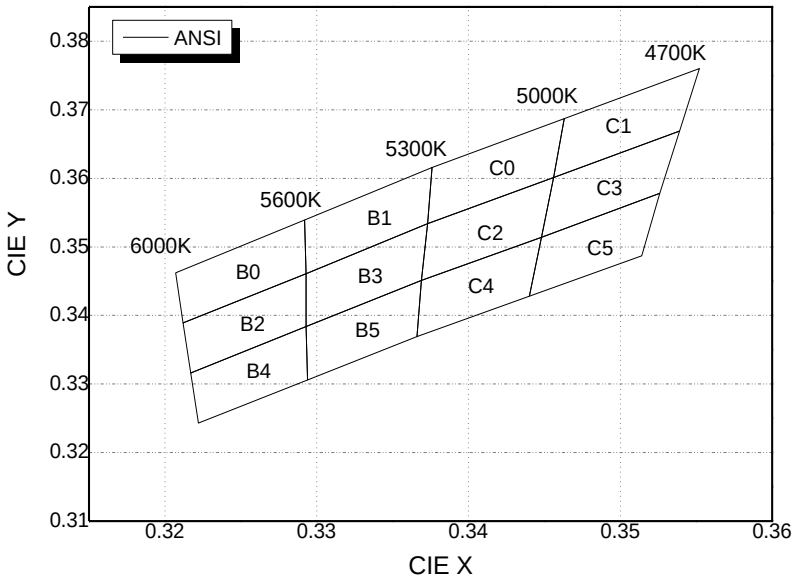
Color Bin Structure

Table 4. Bin Code description

Part Number	Luminous Flux (lm) @ I_F = 350mA			Color Chromaticity Coordinate @ I_F = 350mA	Typical Forward Voltage (V_F)		
	Bin Code	Min.	Max.		Bin Code	Min.	Max.
SDW02F1C	G1	1400	1600	Refer to page.13	D	32.0	36.0
	G2	1600	1800		E	36.0	40.0
	H1	1800	2400				
SDW82F1C	F2	1250	1400	Refer to page.14	D	32.0	36.0
	G1	1400	1600		E	36.0	40.0
	G2	1600	1800				

Color Bin Structure

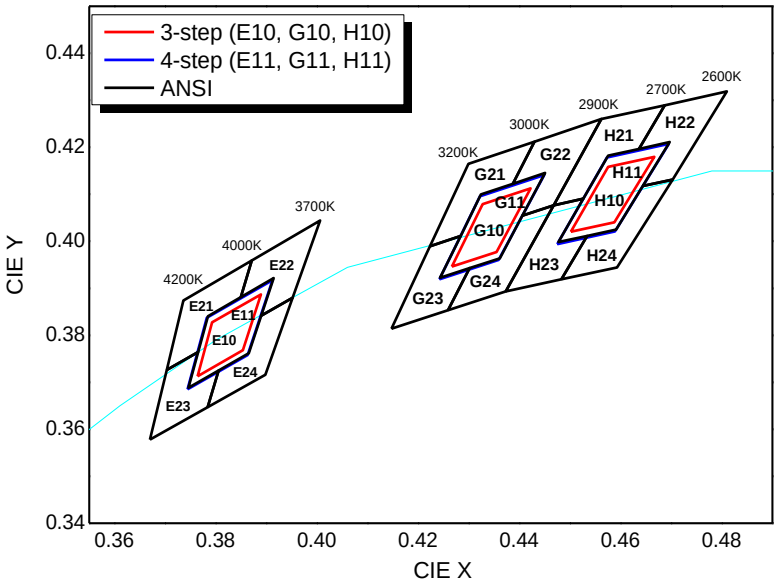
CIE Chromaticity Diagram (Cool white), T_c = 25℃, I_F = 350mA



B0		B1		B2		B3		B4	
CIE x	CIE y	CIE x	CIE y	CIE x	CIE y	CIE x	CIE y	CIE x	CIE y
0.3207	0.3462	0.3292	0.3539	0.3212	0.3389	0.3293	0.3461	0.3217	0.3316
0.3212	0.3389	0.3293	0.3461	0.3217	0.3316	0.3293	0.3384	0.3222	0.3243
0.3293	0.3461	0.3373	0.3534	0.3293	0.3384	0.3369	0.3451	0.3294	0.3306
0.3292	0.3539	0.3376	0.3616	0.3293	0.3461	0.3373	0.3534	0.3293	0.3384
B5		**B6**		**B7**		**B8**		**B9**	
CIE x	CIE y	CIE x	CIE y	CIE x	CIE y	CIE x	CIE y	CIE x	CIE y
0.3293	0.3384	0.3222	0.3243	0.3294	0.3306	0.3200	0.3572	0.3290	0.3656
0.3294	0.3306	0.3226	0.3178	0.3295	0.3234	0.3207	0.3462	0.3292	0.3539
0.3366	0.3369	0.3295	0.3234	0.3364	0.3288	0.3292	0.3539	0.3376	0.3616
0.3369	0.3451	0.3294	0.3306	0.3366	0.3369	0.3290	0.3656	0.3381	0.3740
C0		**C1**		**C2**		**C3**		**C4**	
CIE x	CIE y	CIE x	CIE y	CIE x	CIE y	CIE x	CIE y	CIE x	CIE y
0.3376	0.3616	0.3463	0.3687	0.3373	0.3534	0.3456	0.3601	0.3369	0.3451
0.3373	0.3534	0.3456	0.3601	0.3369	0.3451	0.3448	0.3514	0.3366	0.3369
0.3456	0.3601	0.3539	0.3669	0.3448	0.3514	0.3526	0.3578	0.3440	0.3428
0.3463	0.3687	0.3552	0.3760	0.3456	0.3601	0.3539	0.3669	0.3448	0.3514
C5		**C6**		**C7**		**C8**		**C9**	
CIE x	CIE y	CIE x	CIE y	CIE x	CIE y	CIE x	CIE y	CIE x	CIE y
0.3448	0.3514	0.3366	0.3369	0.3440	0.3428	0.3381	0.3740	0.3470	0.3810
0.3440	0.3428	0.3364	0.3288	0.3433	0.3345	0.3376	0.3616	0.3463	0.3687
0.3514	0.3487	0.3433	0.3345	0.3500	0.3400	0.3463	0.3687	0.3552	0.3760
0.3526	0.3578	0.3440	0.3428	0.3514	0.3487	0.3470	0.3810	0.3572	0.3891

Color Bin Structure

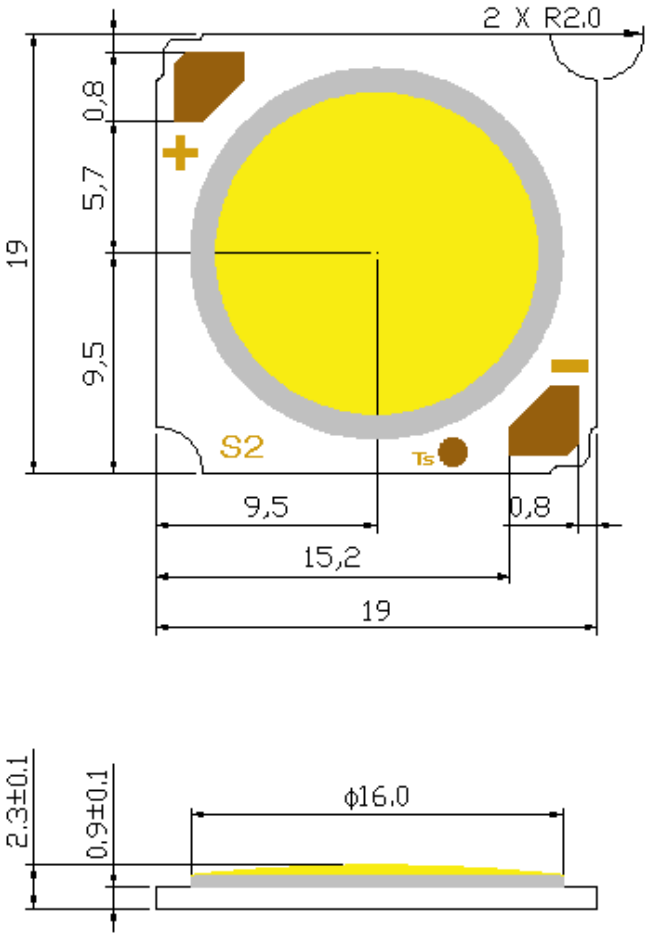
CIE Chromaticity Diagram (Warm white), T_c = 25℃, I_F = 350mA

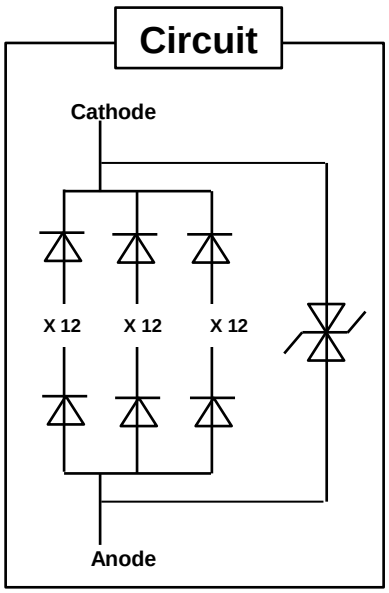


3-STEP						4-STEP					
E10		G10		H10		E11		G11		H11	
CIE x	CIE y	CIE x	CIE y	CIE x	CIE y	CIE x	CIE y	CIE x	CIE y	CIE x	CIE y
0.3764	0.3713	0.4267	0.3946	0.4502	0.4020	0.3744	0.3685	0.4242	0.3919	0.4475	0.3994
0.3793	0.38275	0.4328	0.4079	0.4576	0.4158	0.3782	0.3837	0.4322	0.4096	0.4573	0.4178
0.3890	0.3887	0.4422	0.4113	0.4667	0.4180	0.3912	0.3917	0.4449	0.4141	0.4695	0.4207
0.3854	0.3768	0.4355	0.3977	0.4588	0.4041	0.3863	0.3758	0.4359	0.396	0.4589	0.4021

ANSI							
E21		E22		E23		E24	
CIE x	CIE y	CIE x	CIE y	CIE x	CIE y	CIE x	CIE y
0.3703	0.3726	0.3890	0.3842	0.3670	0.3578	0.3784	0.3647
0.3736	0.3874	0.3914	0.3922	0.3703	0.3726	0.3806	0.3725
0.3871	0.3959	0.3849	0.3881	0.3765	0.3765	0.3865	0.3762
0.3849	0.3881	0.3871	0.3959	0.3746	0.3689	0.3890	0.3842
0.3784	0.3841	0.4006	0.4044	0.3806	0.3725	0.3952	0.3880
0.3765	0.3765	0.3952	0.3880	0.3784	0.3647	0.3898	0.3716
G21		G22		G23		G24	
CIE x	CIE y	CIE x	CIE y	CIE x	CIE y	CIE x	CIE y
0.4223	0.3990	0.4406	0.4055	0.4147	0.3814	0.4259	0.3853
0.4299	0.4165	0.4451	0.4145	0.4223	0.3990	0.4302	0.3943
0.4430	0.4212	0.4387	0.4122	0.4284	0.4011	0.4361	0.3964
0.4387	0.4122	0.4430	0.4212	0.4243	0.3922	0.4406	0.4055
0.4324	0.4100	0.4562	0.4260	0.4302	0.3943	0.4468	0.4077
0.4284	0.4011	0.4468	0.4077	0.4259	0.3853	0.4373	0.3893
H21		H22		H23		H24	
CIE x	CIE y	CIE x	CIE y	CIE x	CIE y	CIE x	CIE y
0.4468	0.4077	0.4644	0.4118	0.4373	0.3893	0.4483	0.3919
0.4562	0.4260	0.4697	0.4211	0.4468	0.4077	0.4534	0.4012
0.4687	0.4289	0.4636	0.4197	0.4526	0.4090	0.4591	0.4025
0.4636	0.4197	0.4687	0.4289	0.4477	0.3998	0.4644	0.4118
0.4575	0.4182	0.4810	0.4319	0.4534	0.4012	0.4703	0.4132
0.4526	0.4090	0.4703	0.4132	0.4483	0.3919	0.4593	0.3944

Mechanical Dimensions

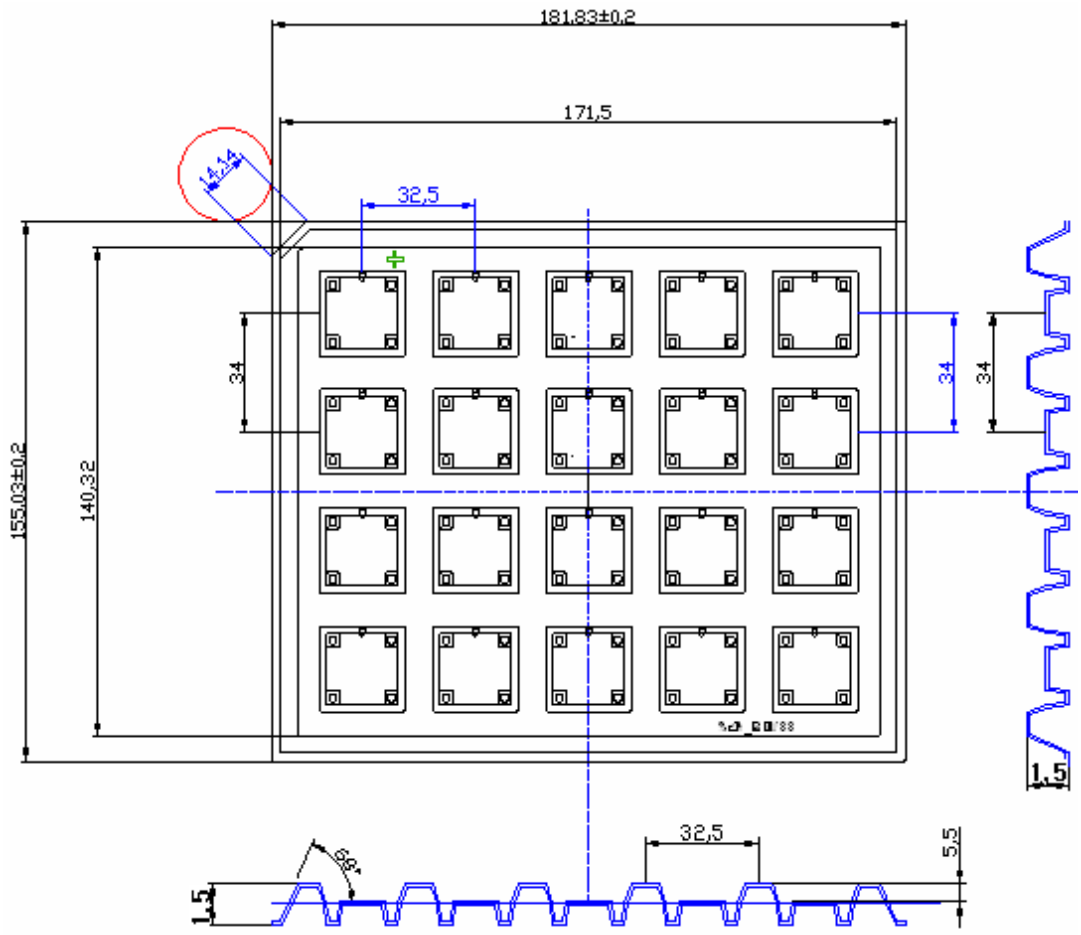




Notes :

(1) All dimensions are in millimeters.
(2) Scale : none
(3) Undefined tolerance is ±0.2mm

Packaging Specification



Notes :

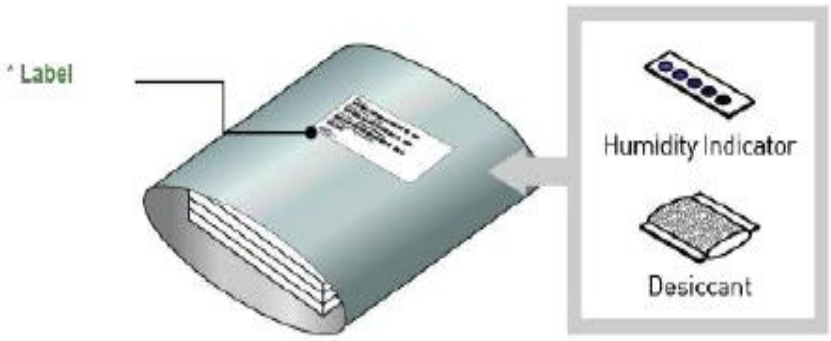
(1) Quantity : 20pcs/Tray

(2) All dimensions are in millimeters (tolerance : ±0.3)

(3) Scale none

Packaging Specification

Aluminum Bag



Outer Box

Notes :

(1) Heat Sealed after packing (Use Zipper Bag)

(2) Quantity : 3Tray(60pcs) /Bag

Product Nomenclature

Table 5. Part Numbering System : $X_1X_2X_3\ X_4X_5\ X_6X_7\ X_8$

Part Number Code	Description	Part Number	Value
X_1	Company	S	
X_2	Package series	D	
X_3X_4	Color Specification	W0	White
		W8	CRI 80
X_5	Series number	2	
X_6	Lens type	F	Flat
X_7	PCB type	1	PCB
X_8	Revision number	C	New COB type

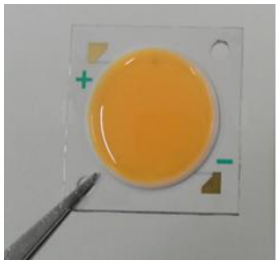
Table 6. Lot Numbering System : $Y_1Y_2Y_3Y_4Y_5Y_6 - Y_7Y_8Y_9Y_{10} - Y_{11}Y_{12}Y_{13}$

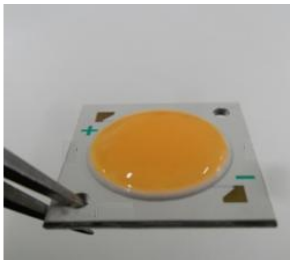
Lot Number Code	Description	Lot Number	Value
Y_1Y_2	Year		
Y_3Y_4	Month		
Y_5Y_6	Day		
$Y_7Y_8Y_9Y_{10}$	Mass order		
$Y_{11}Y_{12}Y_{13}$	Tray No.		

Handling of Silicone Resin for LEDs

(1) During processing, mechanical stress on the surface should be minimized as much as possible. Sharp objects of all types should not be used to pierce the sealing compound.

(2) In general, LEDs should only be handled from the side. By the way, this also applies to LEDs without a silicone sealant, since the surface can also become scratched.





(3) Silicone differs from materials conventionally used for the manufacturing of LEDs. These conditions must be considered during the handling of such devices. Compared to standard encapsulants, silicone is generally softer, and the surface is more likely to attract dust. As mentioned previously, the increased sensitivity to dust requires special care during processing. In cases where a minimal level of dirt and dust particles cannot be guaranteed, a suitable cleaning solution must be applied to the surface after the soldering of wire.

(4) Seoul Semiconductor suggests using isopropyl alcohol for cleaning. In case other solvents are used, it must be assured that these solvents do not dissolve the package or resin. Ultrasonic cleaning is not recommended. Ultrasonic cleaning may cause damage to the LED.

(5) Please do not mold this product into another resin (epoxy, urethane, etc) and do not handle this product with acid or sulfur material in sealed space.

(6) Avoid leaving fingerprints on silicone resin parts.

Precaution for Use

(1) Storage

To avoid the moisture penetration, we recommend storing Power LEDs in a dry box with a desiccant.

The recommended storage temperature range is 5C to 30C and a maximum humidity of 50%.

(2) Use Precaution after Opening the Packaging. Pay attention to the following:

a. Recommend conditions after opening the package

- Sealing
- Temperature : 5 ~ 40℃ Humidity : less than RH30%

b. If the package has been opened more than 4 week or the color of the desiccant changes.

(3) For manual soldering

Seoul Semiconductor recommends the soldering condition

(ZC series product is not adaptable to reflow process)

a. Use lead-free soldering

b. Soldering should be implemented using a soldering equipment at temperature lower than 350˚C.

c. Before proceeding the next step, product temperature must be stabilized at room temperature.

(4) Components should not be mounted on warped (non coplanar) portion of PCB.

(5) Radioactive exposure is not considered for the products listed here in.

(6) It is dangerous to drink the liquid or inhale the gas generated by such products when chemically disposed of.

(7) This device should not be used in any type of fluid such as water, oil, organic solvent and etc. When washing is required, IPA (Isopropyl Alcohol) should be used.

(8) When the LEDs are in operation the maximum current should be decided after measuring the package temperature.

(9) LEDs must be stored properly to maintain the device. If the LEDs are stored for 3 months or more after being shipped from Seoul Semiconductor,

a sealed container with vacuum atmosphere should be used for storage.

(10) The appearance and specifications of the product may be modified for improvement without notice.

Precaution for Use

(11) Long time exposure of sun light or occasional UV exposure will cause silicone discoloration.

(12) Attaching LEDs, do not use adhesive that outgas organic vapor.

(13) The driving circuit must be designed to allow forward voltage only when it is ON or OFF. If the reverse voltage is applied to LED, migration can be generated resulting in LED damage.

(14) Please do not touch any of the circuit board, components or terminals with bare hands or metal while circuit is electrically active.

(15) VOCs (Volatile organic compounds) emitted from materials used in the construction of fixtures can penetrate silicone encapsulants of LEDs and discolor when exposed to heat and photonic energy. The result can be a significant loss of light output from the fixture. Knowledge of the properties of the materials selected to be used in the construction of fixtures can help prevent these issues.

(16) LEDs are sensitive to Electro-Static Discharge (ESD) and Electrical Over Stress (EOS). Below is a list of suggestions that Seoul Semiconductor purposes to minimize these effects.

a. ESD (Electro Static Discharge)

Electrostatic discharge (ESD) is the defined as the release of static electricity when two objects come into contact. While most ESD events are considered harmless, it can be an expensive problem in many industrial environments during production and storage. The damage from ESD to an LEDs may cause the product to demonstrate unusual characteristics such as:

- Increase in reverse leakage current lowered turn-on voltage
- Abnormal emissions from the LED at low current

The following recommendations are suggested to help minimize the potential for an ESD event.
One or more recommended work area suggestions:

- Ionizing fan setup
- ESD table/shelf mat made of conductive materials
- ESD safe storage containers

One or more personnel suggestion options:
- Antistatic wrist-strap
- Antistatic material shoes
- Antistatic clothes

Environmental controls:
- Humidity control (ESD gets worse in a dry environment)

Precaution for Use

b. EOS (Electrical Over Stress)

Electrical Over-Stress (EOS) is defined as damage that may occur when an electronic device is subjected to a current or voltage that is beyond the maximum specification limits of the device. The effects from an EOS event can be noticed through product performance like:

- Changes to the performance of the LED package
  (If the damage is around the bond pad area and since the package is completely encapsulated the package may turn on but flicker show severe performance degradation.)
- Changes to the light output of the luminaire from component failure
- Components on the board not operating at determined drive power

Failure of performance from entire fixture due to changes in circuit voltage and current across total circuit causing trickle down failures. It is impossible to predict the failure mode of every LED exposed to electrical overstress as the failure modes have been investigated to vary, but there are some common signs that will indicate an EOS event has occurred:

- Damaged may be noticed to the bond wires (appearing similar to a blown fuse)
- Damage to the bond pads located on the emission surface of the LED package
  (shadowing can be noticed around the bond pads while viewing through a microscope)
- Anomalies noticed in the encapsulation and phosphor around the bond wires
- This damage usually appears due to the thermal stress produced during the EOS event

c. To help minimize the damage from an EOS event Seoul Semiconductor recommends utilizing:

- A surge protection circuit
- An appropriately rated over voltage protection device
- A current limiting device

Company Information

Published by

Company Information

Seoul Semiconductor (www.SeoulSemicon.com) manufacturers and packages a wide selection of light emitting diodes (LEDs) for the automotive, general illumination/lighting, Home appliance, signage and back lighting markets. The company is the world's fifth largest LED supplier, holding more than 10,000 patents globally, while offering a wide range of LED technology and production capacity in areas such as "nPola", "Acrich", the world's first commercially produced AC LED, and "Acrich MJT - Multi-Junction Technology" a proprietary family of high-voltage LEDs.

The company's broad product portfolio includes a wide array of package and device choices such as Acrich and Acirch2, high-brightness LEDs, mid-power LEDs, side-view LEDs, and through-hole type LEDs as well as custom modules, displays, and sensors.

Legal Disclaimer

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